#### 503891190 06/28/2016

### PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3937841

| SUBMISSION TYPE:      | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT     |

#### **CONVEYING PARTY DATA**

| Name              | Execution Date |  |
|-------------------|----------------|--|
| Chien-Ming Lai    | 08/27/2014     |  |
| Chien-Chung Huang | 08/27/2014     |  |
| Yu-Ting Tseng     | 08/27/2014     |  |
| Ya-Huei Tsai      | 08/27/2014     |  |
| Yu-Ping Wang      | 08/27/2014     |  |

#### RECEIVING PARTY DATA

| Name:           | UNITED MICROELECTRONICS CORP.                       |
|-----------------|---|
| Street Address: | No.3, Li-Hsin Road 2, Science-Based Industrial Park |
| City:           | Hsin-Chu City                                       |
| State/Country:  | TAIWAN  |

#### **PROPERTY NUMBERS Total: 1**

| Property Type       | Number   |
|---------------------|----------|
| Application Number: | 15194577 |

### **CORRESPONDENCE DATA**

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

Email: Patent.admin.uspto.cr@naipo.com

**Correspondent Name: WINSTON HSU** Address Line 1: P.O.BOX 506

Address Line 4: MERRIFIELD, VIRGINIA 22116

| ATTORNEY DOCKET NUMBER: | NAUP2332USA1 |
|-------------------------|--------------|
| NAME OF SUBMITTER:      | KATE YEH     |
| SIGNATURE:              | /KATE YEH/   |
| DATE SIGNED:            | 06/28/2016   |

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### Title of Invention:

### COMPLEMENTARY METAL OXIDE SEMICONDUCTOR DEVICE AND METHOD OF FORMING THE SAME

| As the below named inventor, I here This declaration is directed to:   | by declare that:  |  |  |             |
|--|---|--|--|-------------|
| ☑ The attached application, or   |   |  |  |             |
| ☐ United States application number   |   | filed o  | on   | , or        |
| ☐ PCT international application  | n number  |  | ed on  | -           |
| The above-identified application was   | made or authorized  | to be made by me.  |  |             |
| I believe that I am the original invent application.   | or or an original join  | t inventor of a claime   | d invention in the   |             |
| I hereby acknowledge that any willfu<br>under18 U.S.C. 1001 by fine or impr  |   |  |  |             |
| In consideration of the payment by   | UNITED MICRO CORP.  | ELECTRONICS  | having a postal add  | dress of    |
| No.3, Li-Hsin Road 2, Science  | -Based Industri   | al Park, Hsin-Chu  | City 300, Taiwar   | 1, R.O.C.   |
| (referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar   |   |  | receipt of which is he   | эгеby       |
| I hereby sell, assign and transfer to a<br>the entire right, title and interest in a<br>invention as above-identified applica<br>invention by the above application of<br>substitutes, or extensions thereof, ar | nd to any and all imp<br>tion and, in and to, a<br>r any continuations, | provements which are<br>all Letters Patent to b<br>continuation-in-part, | e disclosed in the<br>be obtained for said<br>divisions, renewals, |             |
| I hereby covenant that no assignment entered into which would conflict with  |   | or encumbrance has   | been or will be made   | or or       |
| I further covenant that ASSIGNEE w<br>and documents relating to said inver<br>known and accessible to I and will te<br>related thereto and will promptly exe   | ntion and said Letter<br>estify as to the same                          | s Patent and legal ed<br>in any interference, l                          | quivalents as may be<br>litigation proceeding                      |             |
| representatives any and all papers, i<br>maintain, issue and enforce said app<br>equivalents thereof which may be no<br>IN WINTNESS WHEREOF, I have h  | olication, said invent<br>ecessary or desirable                         | ion and said Letters I<br>e to carry out the pro                         | Patent and said poses thereof.                                     | of signing) |
| Note: An application data sheet (PTG inventive entity, must accompany thi  |   |  |  |             |

Page 1 of 10

NPO#NAU-P2332-USA:0 CUST#UMCD-2014-0328

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Chien-Ming Lai

Date:

AUG 27 2014

Signature:

Chien-Mug lai

Page 2 of 10

### Title of Invention:

## COMPLEMENTARY METAL OXIDE SEMICONDUCTOR DEVICE AND METHOD OF FORMING THE SAME

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|---|---|---|---|---|
| ☑ The attached application, or  |   |   |   |   |
| ☐ United States application nu  | mber  | filed   | on  | , or                                    |
| ☐ PCT international application   | n number  | file  | ed on   | *************************************** |
| The above-identified application was  | made or authorized to   | be made by me.  | ***************************************             |   |
| I believe that I am the original invent application.  | or or an original joint inv   | rentor of a claim   | ed invention i                                      | n the                                   |
| I hereby acknowledge that any willfu<br>under18 U.S.C. 1001 by fine or impr   | I false statement made isonment of not more th                                  | n this declaratio<br>an five (5) years                      | n is punishab<br>, or both.                         | le                                      |
| In consideration of the payment by  | UNITED MICROELI   | ECTRONICS   | having a p  | ostal address of                        |
| No.3, Li-Hsin Road 2, Science   | -Based Industrial P   | ark, Hsin-Chu   | <br>u City 300,                                     | Taiwan, R.O.C.                          |
| (referred to as "ASSIGNEE"below) to acknowledged, andfor other good an  | o I of the sum of One Do<br>ad valuable consideration                           | ollar (\$ 1.00), the<br>n.                                  | receipt of wh                                       | ich is hereby                           |
| I hereby sell, assign and transfer to A<br>the entire right, title and interest in ar<br>invention as above-identified applica<br>invention by the above application or<br>substitutes, or extensions thereof, an | nd to any and all improvition and, in and to, all Li<br>any continuations, cont | ements which ar<br>etters Patent to t<br>linuation-in-part, | e disclosed in<br>be obtained for<br>divisions, rer | n the<br>or said<br>newals.             |
| I hereby covenant that no assignmer entered into which would conflict with  | nt, sale, agreement or er<br>n this assignment;                                 | ncumbrance has  | been or will I                                      | be made or                              |
| I further covenant that ASSIGNEE wand documents relating to said inven known and accessible to I and will te related thereto and will promptly executed.  | tion and said Letters Pa<br>stify as to the same in a                           | itent and legal ed<br>ny interference,                      | quivalents as<br>litigation prod                    | may be                                  |
| representatives any and all papers, in<br>maintain, issue and enforce said app<br>equivalents thereof which may be ne<br>IN WINTNESS WHEREOF, I have he   | lication, said invention a<br>cessary or desirable to                           | and said Letters<br>carry out the pro                       | Patent and sa                                       | aid<br>f.<br>_(Date of signing)         |
| Note: An application data sheet (PTC  |   |   |   |   |

Page 3 of 10

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

**Chien-Chung Huang** 

Date:

AUG 27 2014

Signature:

Page 4 of 10

NPO#NAU-P2332-USA:0 CUST#UMCD-2014-0328

### Title of Invention:

### COMPLEMENTARY METAL OXIDE SEMICONDUCTOR DEVICE AND METHOD OF FORMING THE SAME

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| ☑ The attached application, or  |  |  |             |
| ☐ United States application nu  | ımber  | filed on   | , or        |
| ☐ PCT international application   | n number   | filed on   |             |
| The above-identified application was  | s made or authorized to be made  | by me.   |             |
| I believe that I am the original invent<br>application.   | tor or an original joint inventor of   | a claimed invention in the   |             |
| I hereby acknowledge that any willfu<br>under18 U.S.C. 1001 by fine or impi   |  |  |             |
| In consideration of the payment by  | UNITED MICROELECTRO CORP.  | NICS having a postal add   | dress of    |
| No.3, Li-Hsin Road 2, Science   | e-Based Industrial Park, Hs  | in-Chu City 300, Taiwan  | ı, R.O.C.   |
| (referred to as "ASSIGNEE"below) t<br>acknowledged, andfor other good ar  |  | 00), the receipt of which is he  | ereby       |
| I hereby sell, assign and transfer to<br>the entire right, title and interest in a<br>invention as above-identified applica-<br>invention by the above application o<br>substitutes, or extensions thereof, a | nd to any and all improvements wation and, in and to, all Letters Par<br>r any continuations, continuation | which are disclosed in the<br>tent to be obtained for said<br>-in-part, divisions, renewals, |             |
| I hereby covenant that no assignme entered into which would conflict wit  |  | nce has been or will be made   | or          |
| I further covenant that ASSIGNEE wand documents relating to said inventions and accessible to I and will terelated thereto and will promptly exe  | ntion and said Letters Patent and<br>estify as to the same in any interf                                   | legal equivalents as may be erence, litigation proceeding                                    |             |
| representatives any and all papers,<br>maintain, issue and enforce said ap<br>equivalents thereof which may be no<br>IN WINTNESS WHEREOF, I have h  | plication, said invention and said<br>ecessary or desirable to carry out                                   | Letters Patent and said the proposes thereof.  | of signing) |
| Note: An application data sheet (PT<br>inventive entity, must accompany th  |  |  |             |

Page 5 of 10

F#NPO-P0002E-US1201

| LEGAL NAME OF INVENTOR(ASSIGNOR) |               |       |             |  |
|----------------------------------|---------------|-------|-------------|--|
| Inventor:                        | Yu-Ting Tseng | Date: | AUG 27 2014 |  |
| Signature:                       | Yu-Ting Treng |       |             |  |

Page 6 of 10

### Title of Invention:

### COMPLEMENTARY METAL OXIDE SEMICONDUCTOR DEVICE AND METHOD OF FORMING THE SAME

| As the below named inventor, I here This declaration is directed to:   | eby declare that:   |   |        |
|--|---|---|--------|
| ☑ The attached application, or   | •   |   |        |
| ☐ United States application nu   | ımber   | filed on, or  | ٢      |
| ☐ PCT international application  | n number  | filed on  |        |
| The above-identified application was   | s made or authorized to be made   | by me.  |        |
| I believe that I am the original invent application.   | tor or an original joint inventor of a  | a claimed invention in the  |        |
| I hereby acknowledge that any willfu<br>under18 U.S.C. 1001 by fine or impr  | ll false statement made in this derisonment of not more than five (5  | claration is punishable<br>i) years, or both.   |        |
| In consideration of the payment by   | UNITED MICROELECTROICORP.   | NICS having a postal address  | s of   |
| No.3, Li-Hsin Road 2, Science  | e-Based Industrial Park, Hs   | in-Chu City 300, Taiwan, R  | .O.C.  |
| (referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar   | o I of the sum of One Dollar (\$ 1.0<br>nd valuable consideration.  | 00), the receipt of which is hereby   | у      |
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| I hereby covenant that no assignment<br>entered into which would conflict witl   | nt, sale, agreement or encumbrar<br>h this assignment;  | nce has been or will be made or   |        |
| I further covenant that ASSIGNEE wand documents relating to said inver<br>known and accessible to I and will te<br>related thereto and will promptly exe   | ntion and said Letters Patent and<br>estify as to the same in any interfe                                       | legal equivalents as may be erence, litigation proceeding                             |        |
| representatives any and all papers, i<br>maintain, issue and enforce said app<br>equivalents thereof which may be ne<br>IN WINTNESS WHEREOF, I have h  | olication, said invention and said lecessary or desirable to carry out  | Letters Patent and said   | gning) |
| Note: An application data sheet (PTC<br>inventive entity, must accompany thi   |   |   |        |

Page 7 of 10

NPO#NAU-P2332-USA:0 CUST#UMCD-2014-0328

| LEGAL NAM  | NE OF INVENTOR(ASSIGNOR) |       |     |    |      |  |
|------------|--------------------------|-------|-----|----|------|--|
| Inventor:  | Ya-Huei Tsai             | Date: | AUG | 27 | 2014 |  |
| Signature: | Va-Huei Tsaj             |       |     |    |      |  |

Page 8 of 10

### Title of Invention:

## COMPLEMENTARY METAL OXIDE SEMICONDUCTOR DEVICE AND METHOD OF FORMING THE SAME

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| I hereby acknowledge that any willfu<br>under18 U.S.C. 1001 by fine or impr  | I false statement ma<br>isonment of not more                              | de in this declarati<br>e than five (5) year                     | on is punishable<br>rs, or both.                          |   |
| In consideration of the payment by   | UNITED MICROI   | ELECTRONICS  | having a posta  | al address of                           |
| No.3, Li-Hsin Road 2, Science  | -Based Industria  | l Park, Hsin-Cl  | <br>ոս City 300, Tai                                      | iwan, R.O.C                             |
| (referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar   | o I of the sum of One<br>nd valuable considera                            | Dollar (\$ 1.00), thation.                                       | e receipt of which  | is hereby                               |
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| I hereby covenant that no assignmer entered into which would conflict with   | nt, sale, agreement on this assignment;                                   | r encumbrance ha   | is been or will be r                                      | made or                                 |
| I further covenant that ASSIGNEE w<br>and documents relating to said inver<br>known and accessible to I and will te<br>related thereto and will promptly exe   | ition and said Letters<br>estify as to the same i                         | Patent and legal n any interference                              | equivalents as ma   | ay be                                   |
| representatives any and all papers, i<br>maintain, issue and enforce said app<br>equivalents thereof which may be ne<br>IN WINTNESS WHEREOF, I have he   | olication, said invention<br>ecessary or desirable                        | on and said Letters<br>to carry out the p                        | s Patent and said roposes thereof.                        | Date of signing)                        |
| Note: An application data sheet (PTC inventive entity, must accompany thi  | D/SB/14 or equivalen<br>s form. Use this form                             | t), including namir<br>for <u>each additi</u> ons                | ng the entire<br>al inventor.                             |   |

Page 9 of 10

NPO#NAU-P2332-USA:0 CUST#UMCD-2014-0328

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Yu-Ping Wang

Date:

AUG 27 2014

Signature:

Page 10 of 10

F#NPO-P0002E-US1201 DSC0-103U007298

NPO#NAU-P2332-USA:0 CUST#UMCD-2014-0328

**RECORDED: 06/28/2016**